(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
20 November 2003 (20.11.2003)

PCT

(10) International Publication Number
WO 03/096408 A1

(51) International Patent Classification[7]: H01L 21/56, 21/68, C09J 7/02

(21) International Application Number: PCT/NL03/00346

(22) International Filing Date: 12 May 2003 (12.05.2003)

(25) Filing Language: Dutch

(26) Publication Language: English

(30) Priority Data:
1020594 14 May 2002 (14.05.2002) NL

(71) Applicant *(for all designated States except US)*: **FICO B.V.** [NL/NL]; Ratio 6, NL-6921 RW Duiven (NL).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **GAL, Wilhelmus, Gerardus, Jozef** [NL/NL]; Beekseweg 2, NL-7031 AX Kilder (NL). **DE VRIES, Franciscus, Bernardus, Antonius** [NL/NL]; Hasselt 11, NL-7152 KV Eibergen (NL).

(74) Agent: **VAN DEN HEUVEL, Henricus, Theodorus**; Patentwerk B.V., P.O. Box 1514, NL-5200 BN 's-Hertogenbosch (NL).

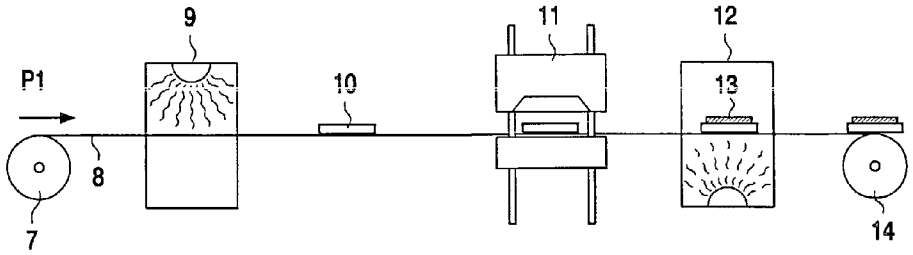
(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD FOR ENCAPSULATING AN ELECTRONIC COMPONENT USING A FOIL LAYER



(57) Abstract: The invention relates to a method for encapsulating an electronic component, in particular a semiconductor, fixed on a carrier, comprising the processing steps of: a) placing at least one foil layer in a mould, b) placing the carrier in contact with the foil layer with the side remote from the component, and c) encapsulating the electronic component with encapsulating material, characterized in that the foil layer undergoes a treatment whereby the adhesion of the foil layer is increased such that it adheres to the carrier. The invention also relates to a foil material for applying during such a method.

WO 03/096408 A1